

ABSTRACT OF THE DISCLOSURE

The invention provides an electrode forming method with steps of arraying chip-style electronic components on an arraying flat bed thereby positioning and  
5 aligning the components, lowering a film coated with an adhesive in relative manner together with an adhering top plate parallel to the arraying flat bed thereby adhering ends of the positioned and aligned chip-style electronic components to the adhesive, then lowering  
10 the first film to which the chip-style electronic components are adhered in relative manner together with a coating top plate parallel to a coating flat bed provided with a conductive paste layer of a constant thickness thereby pressing the other ends of the chip-  
15 style electronic components to the coating flat bed and coating the ends of the electronic components with the conductive paste.